SLOVENSKI STANDARD
SIST EN 123300:2001/A1:1997

01-avgust-1997

Sectional specification: Multilayer printed boards - Amendment to table IV of EN

Sectional Specification: Multilayer printed boards

Rahmenspezifikation: Mehrlagen-Leiterplatten

Spécification intermédiaire: Cartes imprimées multicouches

Ta slovenski standard je istoveten z: **EN 123300:1992/A1:1995**

ICS:

31.180	Tiskana vezja (TIV) in tiskane plošče / Printed circuits and boards

SIST EN 123300:2001/A1:1997 **en**

EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN 123300/A1

August 1995

ICS 31.180

Descriptors: Multilayer printed boards, characteristics, capability test, quality conformance inspection, test patterns

English version

Sectional Specification: Multilayer printed boards

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Cartes imprimées multicouches

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This amendment A1 modifies the European Standard EN 123300:1992; it was approved by CENELEC on 1995-07-04. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this amendment the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This amendment exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

This amendment was prepared by CLC/TC CECC/WG 23.

The text of the draft was submitted to the Unique Acceptance Procedure and was approved by CENELEC as amendment A1 to EN 123300:1992 on 1995-07-04.

The following dates were fixed:

- latest date by which the amendment has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 1996-07-01
- latest date by which the national standards conflicting with the amendment have to be withdrawn (dow) 1996-07-01

Amendment A1 to EN 123300:1992

Introduce the data on pages 3, 4 and 5 of this amendment into table IV of EN 123300.

NOTE: The asterisk denotes a changed or new characteristic.

Table IV

Inspection Group		Characteristic	Test No	Level A IL	Level A AQL	Level C IL	Level C AQL
Group A							
Sub-Group A1		**Visual Inspection**					
		Conformity	1	S2	2.5%	100%	
		Identification	1	S2	2.5%	100%	
		Appearance	1a	S2	2.5%	100%	
		Workmanship	1a	S2	2.5%	100%	
		Plated-through holes	1a	S2	2.5%	100%	
	*	Conductor Defects	1a	S2	2.5%	100%	
	*	Misalignment of Solder Resist and Land	1a	S2	2.5%	100%	
		Particles between conductors	1b, 1c	S2 S2	2.5% 2.5%	100% 100%	
Sub-Group A2		**Dimensional Examination**					
		Board Dimensions	2	S1	4.0%	S4	2.5%
		Holes	2	S1	4.0%	S4	2.5%
		Slots, Notches	2	S1	4.0%	S4	2.5%
		Conductor Width	2	S1	4.0%	S4	2.5%
		Conductor Spacing	2	S1	4.0%	S4	2.5%
		Misalignment of Hole and Land	2	S1	4.0%	S4	2.5%
		Positional Tolerance of Hole Centres	2	S1	4.0%	S4	2.5%
	*	Misalignment of Solder Resist and Land	2a	S1	4.0%	S4	2.5%
Sub-Group A3		Spare group for additional A tests					

Inspection Group		Characteristic	Test No	Level A IL	Level A AQL	Level C IL	Level C AQL
Group B							
Sub-Group B1		Dimensional Interchange -ability					
		Board Thickness in the edge contact zone	2	-	-	S2	2.5%
		Flatness	12a	-	-	S2	2.5%
Sub-Group B2		Solderability					
		Unconditioned	14a	S2	2.5%	S3	2.5%
	*	After Accelerated Aging	20a	-	-	S3	2.5%
Sub-Group B3		Thermal Shock Tests					
	*	Interlaminar Bond	15a	S1	4.0%	S2	2.5%
	*	Through-hole Platings	19c	-	-	S2	2.5%
	*	Heat Sink Bond	15a	-	-	S2	2.5%
Sub-Group B4		Mechanical Tests					
		Peel Strength	10a	-	-	S2	2.5%
		Pull-out strength of landless plated - through holes	11b	-	-	S2	2.5%
Sub Group B5		Surface Finish Tests					
		Adhesion of Plating	#13a	S1	2.5%	S2	2.5%
	*	Thickness of edge	13f	-	-	S2	2.5%
	*	Edge Plating Porosity	#13d	-	-	S2	2.5%
			,13e	-	-	S2	2.5%
Sub-Group B6	*	Internal Short Circuit	4a	-	-	S2	2.5%

Inspection Group		Characteristic	Test No	Level A No of Specimens	Level A Accept: Reject	Level C No of Specimens	Level C Accept: Reject
Group C							
Sub-Group C1		Test Interval: 3 Months					
		Change in Resistance of plated-through holes	3c	-	-	6	1:2
		Change in Resistance of interconnections	3b, 3c	-	-	6	1:2
	*	Insulation Resistance within a layer	6b	-	-	20	1:2
	*	Insulation Resistance between layers	6c	-	-	20	1:2
	*	Insulation Resistance between heat sink and subjacent circuitry	6c	-	-	20	1:2
	*	Insulation Resistance between heat sink and adjacent circuitry	6c	-	-	20	1:2
	*	Process Contamination	#	-	-	20	1:2
	*	Solvent Resistance	#	-	-	6	1:2
	*	Resistance to Solder	#	-	-	6	1:2

NOTES:

1. The symbol # denotes that the testing detail shall be included in the relevant Capability Detail Specification.

2. This listing may be subject to continuing review, as required by the publication of new Capability Detail Specifications.
